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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/695,356	10/27/2003	Shih-Ping Hsu	LA-7452-105.US	6002

167 7590 10/14/2004

FULBRIGHT AND JAWORSKI L L P  
PATENT DOCKETING 29TH FLOOR  
865 SOUTH FIGUEROA STREET  
LOS ANGELES, CA 900172576

EXAMINER
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BEREZNY, NEMA O

ART UNIT	PAPER NUMBER
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2813

DATE MAILED: 10/14/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

**Office Action Summary**

**Application No.**

10/695,356

**Applicant(s)**

HSU ET AL.

**Examiner**

Nema O Berezny

**Art Unit**

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

**Status**

- 1) ☒ Responsive to communication(s) filed on 28 July 2004.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

**Disposition of Claims**

- 4) ☒ Claim(s) 1-20 is/are pending in the application.
- 4a) Of the above claim(s) 1-6 is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 7-20 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

**Application Papers**

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 27 October 2003 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

**Priority under 35 U.S.C. § 119**

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All b) ☐ Some \* c) ☐ None of:
1. ☒ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

**Attachment(s)**

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)  
Paper No(s)/Mail Date \_\_\_\_\_
- 4) ☐ Interview Summary (PTO-413)  
Paper No(s)/Mail Date. \_\_\_\_\_
- 5) ☐ Notice of Informal Patent Application (PTO-152)
- 6) ☐ Other: \_\_\_\_\_

## **DETAILED ACTION**

### ***Election/Restrictions***

Applicant's election of claims 7-20 in the reply filed on 7-28-04 is acknowledged. Because applicant did not distinctly and specifically point out the supposed errors in the restriction requirement, the election has been treated as an election without traverse (MPEP § 818.03(a)). Claims 1-20 are currently pending, with claims 1-6 being non-elected.

### ***Claim Rejections - 35 USC § 102***

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(a) the invention was known or used by others in this country, or patented or described in a printed publication in this or a foreign country, before the invention thereof by the applicant for a patent.

Claims 7-8, 10-12, 14-16, and 18-20 are rejected under 35 U.S.C. 102(a) as being anticipated by Makino et al. (6,566,239). Makino discloses a fabrication method for a semiconductor package substrate having a contact pad protective layer formed thereon, the method comprising the steps of: providing an insulating layer (Figs.1-12 el.13) having a plurality of blind vias formed therein for exposing inner traces (el.12) disposed underneath the insulating layer (col.1 lines 50-54); forming a conductive film (el.14) on the insulating layer and over the blind vias; forming a first resist layer (el.15) on the conductive film, wherein the first resist layer has a plurality of openings (el.16) to

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expose predetermined parts of the conductive film; performing a first electroplating process to form a patterned trace layer (el.17) in the openings and in the blind vias to form conductive vias, wherein the patterned trace layer comprises a plurality of contact pads, and at least one of the contact pads is electrically connected to at least one of the conductive vias (Fig.3; col.1 line 64 – col.2 line 5); forming a second resist layer (el.18) over the patterned trace layer exclusive of the contact pads, making the contact pads exposed from the second resist layer (Fig.5); performing a second electroplating process to form a metal barrier layer (el.21,22) on the contact pads (Fig.8; col.2 lines 20-24, 44-45); and removing the second resist layer (Figs.8-9), the first resist layer (Figs.3-4), and parts of the conductive film covered by the first resist layer (Figs.9-10) **[claims 7, 14]**. Makino also discloses a solder mask (el.26) for covering the patterned trace layer and having a plurality of openings to expose the metal barrier layer (Fig.11) **[claims 8, 15]**; wherein the substrate is a flip-chip package substrate or a wire-bonded package substrate (Fig.12; Fig.24; col.2 lines 37-39; col.8 lines 38-43) **[claims 10, 18]**; wherein the contact pad is selected from the group consisting of a bump solder pad, solder ball pad, and wire-bonded pad (Fig.12) **[claims 11, 19]**; wherein the metal barrier layer is made of a material selected from the group consisting of gold (Au), nickel (Ni), palladium (Pd), silver (Ag), tin (Sn), Ni/Pd, chromium (Cr)/titanium (Ti), NiAu, Pd/Au, and Ni/Pd/Au (col.2 lines 20-24) **[claims 12, 20]**; and wherein the openings of the resist layer correspond in position to the blind vias of the insulating layer (Fig.3) **[claim 16]**.

***Claim Rejections - 35 USC § 103***

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 9 and 17 are rejected under 35 U.S.C. 103(a) as being unpatentable over Makino as applied to claims 7 and 14 above, and further in view of Shinomiya (5,907,786). Makino does not disclose a multi-layered structure. However, Makino would look to one such as Shinomiya for a protective surface because Shinomiya discloses wherein a substrate (Figs.1(b)-1(h) el.11) has a multi-layered structure having a plurality of non-conductive layers (el.12,13), and the insulating layer (el.13) is one of the non-conductive layers formed closest to an outside-exposed surface of the substrate. Therefore, it would have been obvious to a person of ordinary skill in the art at the time of the invention to use the multi-layered structure of Shinomiya with the method of Makino in order to provide a surface protecting film for the device (col.4 lines 9-10).

Claim 13 is rejected under 35 U.S.C. 103(a) as being unpatentable over Makino as applied to claim 7 above, and further in view of Wang et al. (2004/0000427). Makino does not specifically disclose a dry or liquid photoresist film. However, Makino would look to one such as Wang for application versatility because Wang discloses wherein the first or second resist layer is a dry photoresist film or a liquid photoresist (p.5

para.39). Therefore, it would have been obvious to a person of ordinary skill in the art at the time of the invention to use the photoresist of Wang with the method of Makino; wherein a dry or liquid photoresist can be applied by several different methods and used under a variety of conditions (p.5 para.39).


### ***Conclusion***

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Nema O Berezny whose telephone number is (571) 272-1686. The examiner can normally be reached on M-F 9-5:30.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead, Jr. can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

NB

  
Nema Berezny